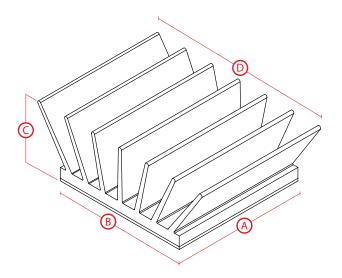


# **High Performance ASIC Cooling Solutions w/Thermal Tape Attachment**

# ATS PART # ATS-56002-C3-R0

## **Features & Benefits**

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- Designed specifically for ASIC package and their unique cooling requirements
- Comes preassembled with high performance thermal interface material





# **Thermal Performance**

\*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	9	5.2	
300	1.5	7.5		
400	2.0	6		
500	2.5	5.5		
600	3.0	5		
700	3.5	4.5		
800	4.0	3.9		

### **Product Details**

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
25 mm	25 mm	4 mm	28.1 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).